



CyberOptics Demonstrates Industry-Leading Airborne Particle and Ultra High-Resolution MRS Sensors at SEMICON Europa

Significantly Improving Yields and Tool Uptime in Semiconductor Fabs Worldwide

Minneapolis, MN— October 2018 — CyberOptics® Corporation (NASDAQ: CYBE), a leading global developer and manufacturer of high precision 3D sensing technology solutions, announces that it will exhibit at [SEMICON Europa](#), scheduled to take place Nov. 13-16, 2018 at the Messe Munchen in Munich, Germany. The company will demonstrate its next-generation Airborne Particle Sensor™ technology (APS3) 300mm with new ParticleSpectrum™ software in Hall A4, booth 101.

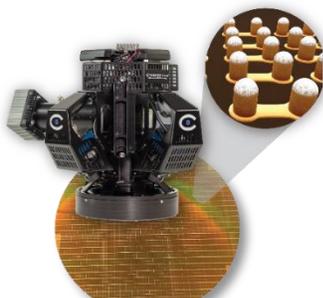
CyberOptics' WaferSense® [APS3](#) speeds up equipment set-up and long-term yields in semiconductor fabs by wirelessly detecting, identifying and monitoring airborne particles. Now in a thinner and lighter form factor to travel through semiconductor tools with ease, the APS3 offers leading accuracy and sensitivity valued by equipment and process engineers.



“Semiconductor Fabs worldwide have been utilizing our Airborne Particle Sensor technology for many years,” said Dr. Subodh Kulkarni, President and CEO, CyberOptics. “Now in its third generation, we will continue to deliver significant benefits in terms of yield, productivity and throughput.”

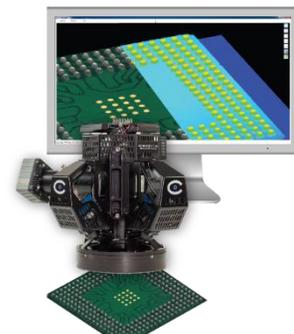
The APS3 solution incorporates ParticleSpectrum software – a completely new, touch-enabled interface with user-friendly functionality, making it simple to read, record and review small to large airborne particle data and see the effects of cleanings, adjustments and repairs in real-time.

At SEMICON Europa, CyberOptics also will demonstrate the proprietary 3D Ultra High-Resolution Multi-Reflection Suppression (MRS) Sensor technology that meticulously identifies and rejects reflections caused by shiny components and surfaces. Effective suppression of multiple reflections is critical for highly accurate measurements. Offering an unmatched combination of accuracy and speed, MRS sensors are widely used for inspection and measurement in the SMT,



Wafer Bump Inspection

metrology and in semiconductor markets. This best-in-class, ultra high-resolution technology used in back-end inspection applications, is ideally suited for IC package, wafer bump inspection and mid-end semiconductor applications where the highest degree of precision is required.



IC Package Inspection

For more information about the entire line of CyberOptics solutions please visit www.cyberoptics.com.

About CyberOptics

CyberOptics Corporation (www.cyberoptics.com) is a leading global developer and manufacturer of high precision sensing technology solutions. CyberOptics' sensors are used in SMT, semiconductor and metrology markets to significantly improve yields and productivity. By leveraging its leading edge technologies, the company has strategically established itself as a global leader in high precision 3D sensors, allowing CyberOptics to further increase its penetration of key vertical markets. Headquartered in Minneapolis, Minnesota, CyberOptics conducts worldwide operations through its facilities in North America, Asia and Europe.

Statements regarding the company's anticipated performance are forward-looking and therefore involve risks and uncertainties, including but not limited to: market conditions in the global SMT and semiconductor capital equipment industries; the timing of orders and shipments of our products, particularly our 3D MRS-enabled AOI systems; increasing price competition and price pressure on our product sales, particularly our SMT systems; the level of orders from our OEM customers; the availability of parts required to meet customer orders; unanticipated product development challenges; the effect of world events on our sales, the majority of which are from foreign customers; rapid changes in technology in the electronics and semiconductor markets; product introductions and pricing by our competitors; the success of our 3D technology initiatives; the market acceptance of our SQ3000 3D CMM system, products for semiconductor mid-end and advanced packaging inspection applications and CyberGage360 product; costly and time consuming litigation with third parties related to intellectual property infringement; and other factors set forth in the company's filings with the Securities and Exchange Commission.

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